MX23C6411

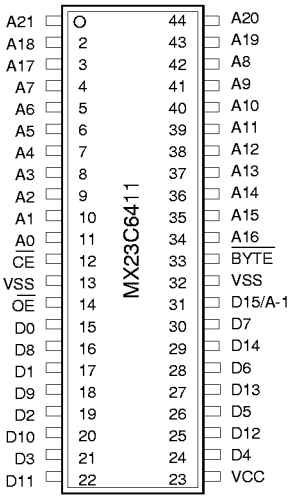
64M-BIT MASK ROM (8/16 BIT OUTPUT)

FEATURES

- Bit organization
  - 8M x 8 (byte mode)
  - 4M x 16 (word mode)
- Fast access time
  - Random access: 120ns (max.)
  - Page access: 50ns (max.)
- Page Size
  - 8 words per page
- Current
  - Operating: 100mA (max.)
  - Standby: 100㎂ (max.)
- Supply voltage
  - 5V ± 10%
- Package
  - 44 pin SOP (500 mil)
  - 48 pin TSOP (20mm x 12mm)

PIN CONFIGURATION

44 SOP



ORDER INFORMATION

Part No.	Access Time	Page Access Time	Package
MX23C6411MC-12	120ns	50ns	44 pin SOP
MX23C6411TC-12	120ns	50ns	48 pin TSOP
MX23C6411RC-12	120ns	50ns	48 pin TSOP (Reverse type)

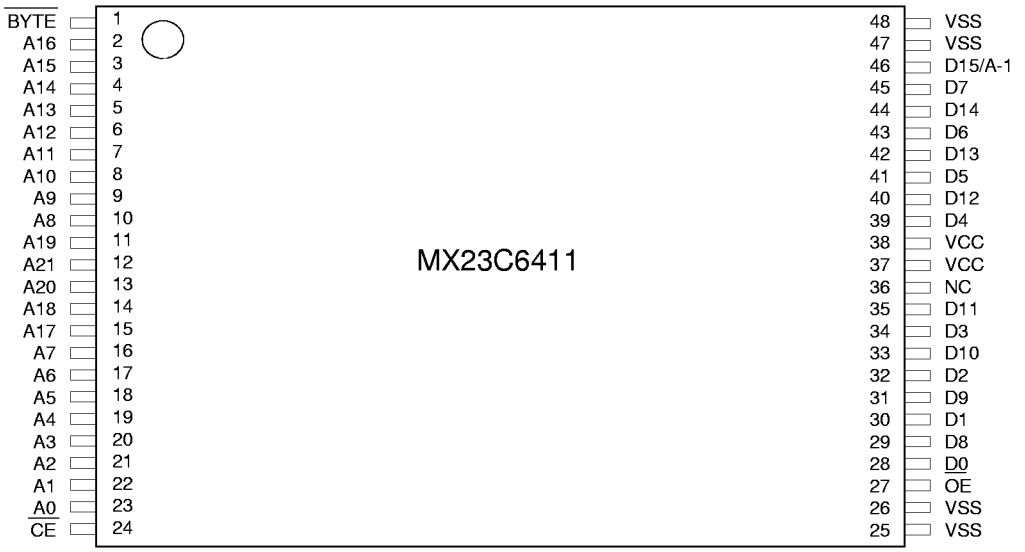
PIN DESCRIPTION

Symbol	Pin Function
A0~A21	Address Inputs
D0~D14	Data Outputs
D15/A-1	D15 (Word Mode) / LSB Address (Byte Mode)
$\overline{CE}$	Chip Enable Input
$\overline{OE}$	Output Enable Input
$\overline{Byte}$	Word / Byte Mode Selection
VCC	Power Supply Pin
VSS	Ground Pin
NC	No Connection

MODE SELECTION

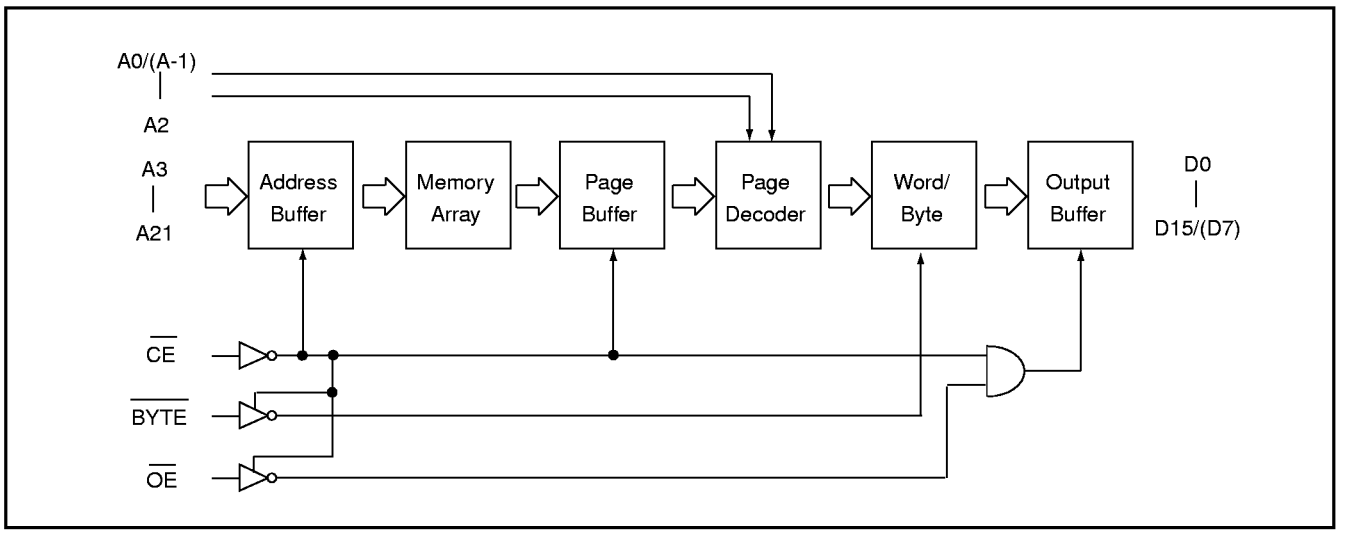
$\overline{CE}$	$\overline{OE}$	$\overline{Byte}$	D15/A-1	D0~D7	D8~D15	Mode	Power
H	X	X	X	High Z	High Z	-	Stand-by
L	H	X	X	High Z	High Z	-	Active
L	L	H	Output	D0~D7	D8~D15	Word	Active
L	L	L	Input	D0~D7	High Z	Byte	Active

48 TSOP (NORMAL TYPE)



48 TSOP (REVERSE TYPE)

BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Ratings
Voltage on any Pin Relative to VSS	VIN	-0.8V to VCC+2.0V (Note)
Ambient Operating Temperature	Topr	0℃ to 70℃
Storage Temperature	Tstg	-65℃ to 125℃

Note : Minimum DC voltage on input or I/O pins is -0.5V. During voltage transitions, inputs may undershoot VSS to -0.8V for periods of up to 20ns. Maximum DC voltage on input or I/O pins is VCC + 0.5V. During voltage transitions, inputs may overshoot VCC to VCC + 2.0V for periods of up to 20ns.

DC CHARACTERISTICS (Ta = 0℃~70℃, VCC = 5V ± 10%)

Item	Symbol	MIN.	MAX.	Conditions
Output High Voltage	VOH	2.4V	-	IOH = -1.0mA
Output Low Voltage	VOL	-	0.4V	IOL = 2.1mA
Input High Voltage	VIH	2.2V	VCC+0.3V	
Input Low Voltage	VIL	-0.3V	0.8V	
Input Leakage Current	ILI	-	10uA	0V, VCC
Output Leakage Current	ILO	-	10uA	0V, VCC
Operating Current	ICC1	-	100mA	tRC = 120ns, all output open, with normal sequential access testing pattern
Standby Current (TTL)	ISTB1	-	1mA	$\overline{CE}$ = VIH
Standby Current (CMOS)	ISTB2	-	100uA	$\overline{CE}$ > VCC - 0.2V
Input Capacitance	CIN	-	10pF	Ta = 25℃, f = 1MHz
Output Capacitance	COUT	-	10pF	Ta = 25℃, f = 1MHz

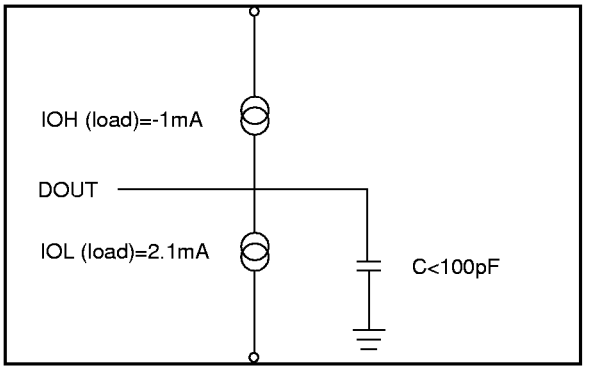
AC CHARACTERISTICS (Ta = 0° C~70° C, VCC = 5V ± 10%)

Item	Symbol	23C6411-12	
		MIN.	MAX.
Read Cycle Time	tRC	120ns	-
Address Access Time	tAA	-	120ns
Chip Enable Access Time	tACE	-	120ns
Page Mode Access Time	tPA	-	50ns
Output Enable Time	tOE	-	50ns
Output Hold After Address	tOH	0ns	-
Output High Z Delay	tHZ	-	20ns

Note : Output high-impedance delay (tHZ) is measured from $\overline{OE}$ or $\overline{CE}$ going high, and this parameter guaranteed by design over the full voltage and temperature operating range - not tested.

AC Test Conditions

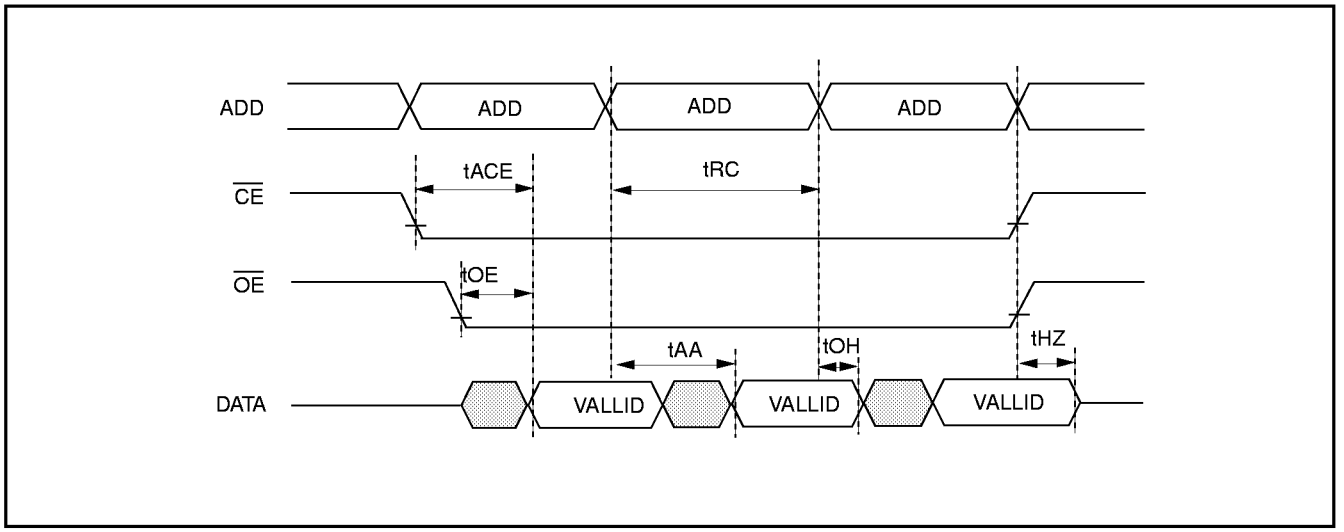
- Input Pulse Levels : 0.4V~3.0V
- Input Rise and Fall Times : 10ns
- Input Timing Level : 1.5V
- Output Timing Level : 0.8V and 2.0V
- Output Load : See Figure



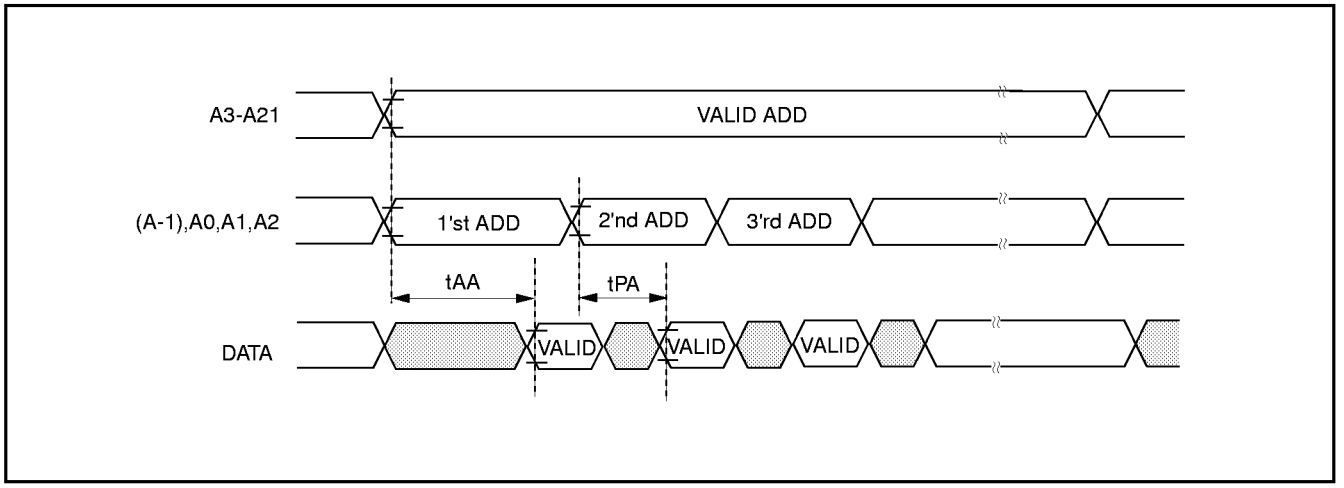
Note:No output loading is present in tester load board.
Active loading is used and under software programming control.
Output loading capacitance includes load board's and all stray capacitance.

TIMING DIAGRAM

RANDOM READ



PAGE READ



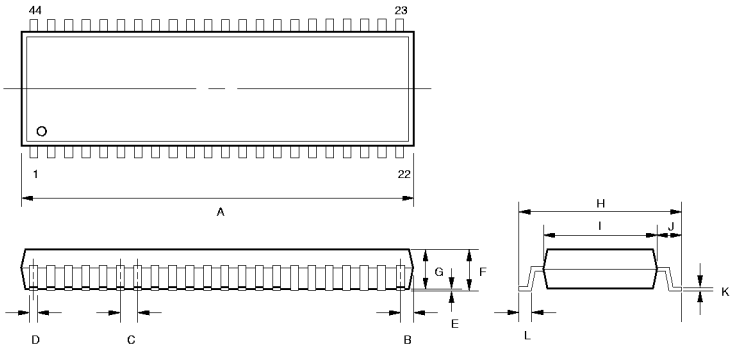
Note:$\overline{CE}$,$\overline{OE}$ are enable. The Page size is 8 words in 16-bit mode, 16 bytes in 8-bit mode.

PACKAGE INFORMATION

44-PIN PLASTIC SOP

ITEM	MILLIMETERS	INCHES
A	28.70 max.	1.130 max.
B	1.10 [REF]	.043 [REF]
C	1.27 [TP]	.050 [TP]
D	.40 ± .10 [Typ.]	.016 ± .004 [Typ.]
E	.010 min.	.004 min.
F	3.00 max.	.118 max.
G	2.80 ± .13	.110 ± .005
H	16.04 ± .30	.631 ± .012
I	12.60	.496
J	1.72	.068
K	.15 ± .10 [Typ.]	.006 ± .004 [Typ.]
L	.80 ± .20	.031 ± .008

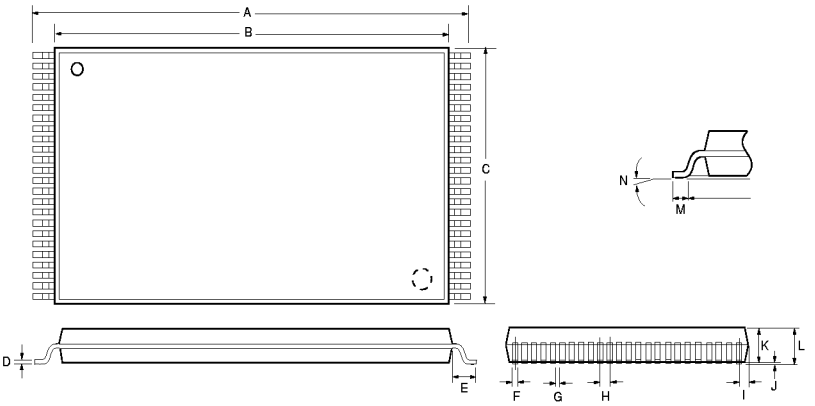
NOTE: Each lead centerline is located within .25 mm[.01 inch] of its true position [TP] at maximum material condition.



48-PIN PLASTIC TSOP

ITEM	MILLIMETERS	INCHES
A	20.0 ± .20	.787 ± .008
B	18.40 ± .10	.724 ± .004
C	12.20 max.	.480 max.
D	0.15 [Typ.]	.006 [Typ.]
E	.80 [Typ.]	.031 [Typ.]
F	.20 ± .10	.008 ±.004
G	.30 ± .10	.012 ± .004
H	.50 [Typ.]	.020 [Typ.]
I	.45 max.	.018 max.
J	0 ~ .20	0 ~ .008
K	1.00 ± .10	.039 ± .004
L	1.27 max.	.050 max.
M	.50	.020
N	0 ~ 5°	.500

NOTE: Each lead centerline is located within .25 mm[.01 inch] of its true position [TP] at maximum material condition.



REVISION HISTORY

REVISION	DESCRIPTION	PAGE	DATE
1.9	AC CHARACTERISTICS tOH 10ns-->0ns	P4	FEB/02/1999